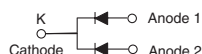


## High Current Density Surface Mount Schottky Barrier Rectifier

### eSMP™ Series



### TO-277A (SMPC)



### FEATURES

- Very low profile - typical height of 1.1 mm
- Ideal for automated placement
- Low forward voltage drop, low power losses
- High efficiency
- Low thermal impedance
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- **Halogen-free according to IEC 61249-2-21 definition**

AUTOMOTIVE  
GRADE  
Available



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 6.0 A
$V_{RRM}$	40 V
$I_{FSM}$	150 A
$E_{AS}$	20 mJ
$V_F$ at $I_F = 6.0$ A	0.40 V
$T_J$ max.	125 °C

### TYPICAL APPLICATIONS

For use in low voltage high frequency inverters, freewheeling, DC/DC converters and polarity protection applications.

### MECHANICAL DATA

**Case:** TO-277A (SMPC)

Molding compound meets UL 94 V-0 flammability rating  
Base P/N-M3 - halogen-free, RoHS compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS compliant, and automotive grade

**Terminals:** Matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 1A whisker test, HM3 suffix meets JESD 201 class 2 whisker test

MAXIMUM RATINGS ( $T_A = 25$ °C unless otherwise noted)			
PARAMETER	SYMBOL	SS12P4C	UNIT
Device marking code		S124C	
Maximum repetitive peak reverse voltage	$V_{RRM}$	40	V
Maximum average forward rectified current (fig. 1) <sup>(1)</sup>	$I_{F(AV)}$	total device	12
		per diode	6.0
Maximum average forward rectified current <sup>(2)</sup>	$I_{F(AV)}$	3.5	A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load per diode	$I_{FSM}$	150	A
Non-repetitive avalanche energy at $T_J = 25$ °C, $L = 60$ mH per diode	$E_{AS}$	20	mJ
Peak repetitive reverse current at $t_p = 2$ μs, 1 kHz, at $T_J = 25$ °C per diode	$I_{RRM}$	1.0	A
Operating junction and storage temperature range	$T_J, T_{STG}$	- 55 to + 125	°C

### Notes

<sup>(1)</sup> Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink

<sup>(2)</sup> Free air, mounted on recommended copper pad area



ELECTRICAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage per diode	I <sub>F</sub> = 1 A	T <sub>A</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.34	-	V
	I <sub>F</sub> = 3 A			0.40	-	
	I <sub>F</sub> = 6 A			0.46	0.52	
	I <sub>F</sub> = 1 A	T <sub>A</sub> = 100 °C		0.24	-	
	I <sub>F</sub> = 3 A			0.31	-	
	I <sub>F</sub> = 6 A			0.40	0.45	
Reverse current per diode	Rated V <sub>R</sub>	T <sub>A</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	129	500	μA
		T <sub>A</sub> = 100 °C		11.9	25	mA
Typical junction capacitance per diode	4.0 V, 1 MHz		C <sub>J</sub>	400	-	pF

Notes

- <sup>(3)</sup> Pulse test: 300 μs pulse width, 1 % duty cycle
- <sup>(4)</sup> Pulse test: Pulse width ≤ 40 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise noted)			
PARAMETER	SYMBOL	SS12P4C	UNIT
Typical thermal resistance	R <sub>θJA</sub> <sup>(1)</sup>	100	°C/W
	R <sub>θJM</sub> <sup>(2)</sup>	3	

Notes

- <sup>(1)</sup> Free air, mounted on recommended copper pad area. Thermal resistance R<sub>θJA</sub> - junction to ambient.
- <sup>(2)</sup> Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink. Thermal resistance R<sub>θJM</sub> - junction to mount.

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
SS12P4C-M3/86A	0.10	86A	1500	7" diameter plastic tape and reel
SS12P4C-M3/87A	0.10	87A	6500	13" diameter plastic tape and reel
SS12P4CHM3/86A <sup>(1)</sup>	0.10	86A	1500	7" diameter plastic tape and reel
SS12P4CHM3/87A <sup>(1)</sup>	0.10	87A	6500	13" diameter plastic tape and reel

Note

- <sup>(1)</sup> Automotive grade

RATINGS AND CHARACTERISTICS CURVES

(T<sub>A</sub> = 25 °C unless otherwise noted)

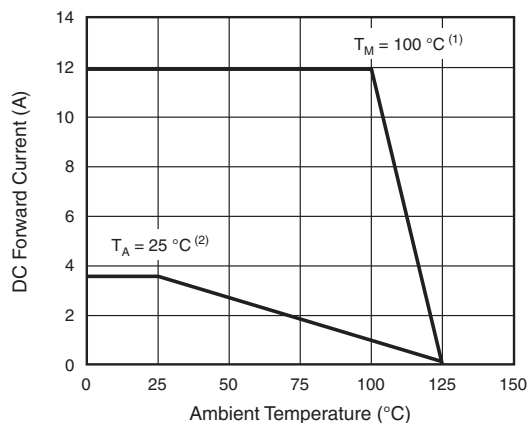


Fig. 1 - Maximum Forward Current Derating Curve

Notes

- Mounted on 30 mm x 30 mm Al PCB with 50 mm x 25 mm x 100 mm fin heat sink, T<sub>M</sub> measured at the terminal of cathode band (R<sub>θJM</sub> = 3 °C/W)
- Free air, mounted on recommended copper pad area (R<sub>θJA</sub> = 100 °C/W)

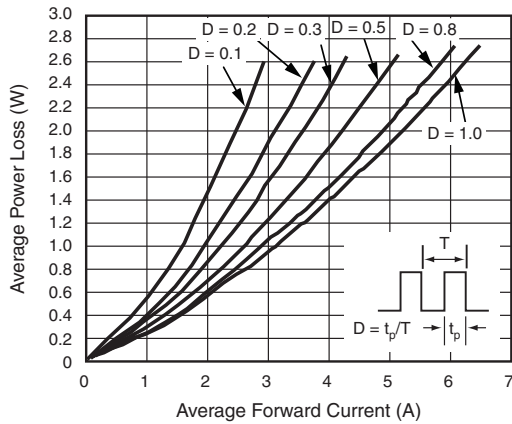


Fig. 2 - Forward Power Loss Characteristics Per Diode

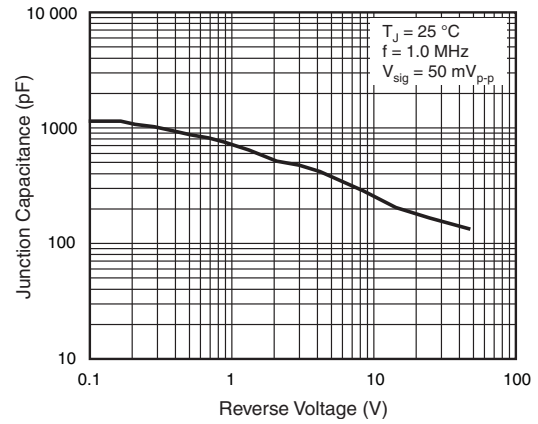


Fig. 5 - Typical Junction Capacitance Per Diode

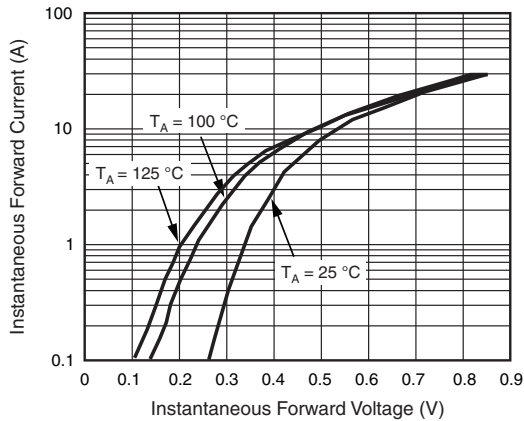


Fig. 3 - Typical Instantaneous Forward Characteristics Per Diode

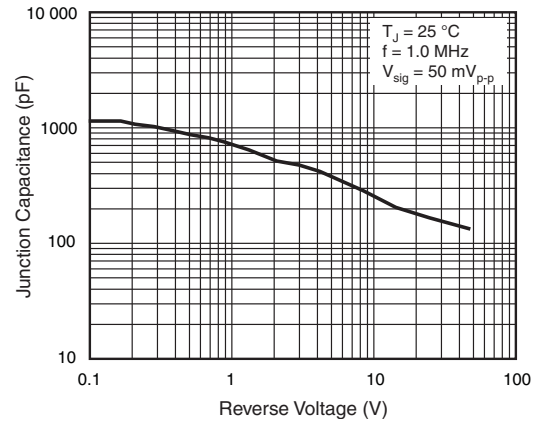


Fig. 6 - Typical Transient Thermal Impedance Per Diode

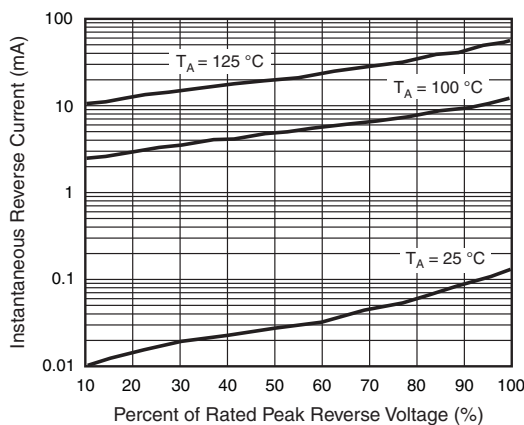


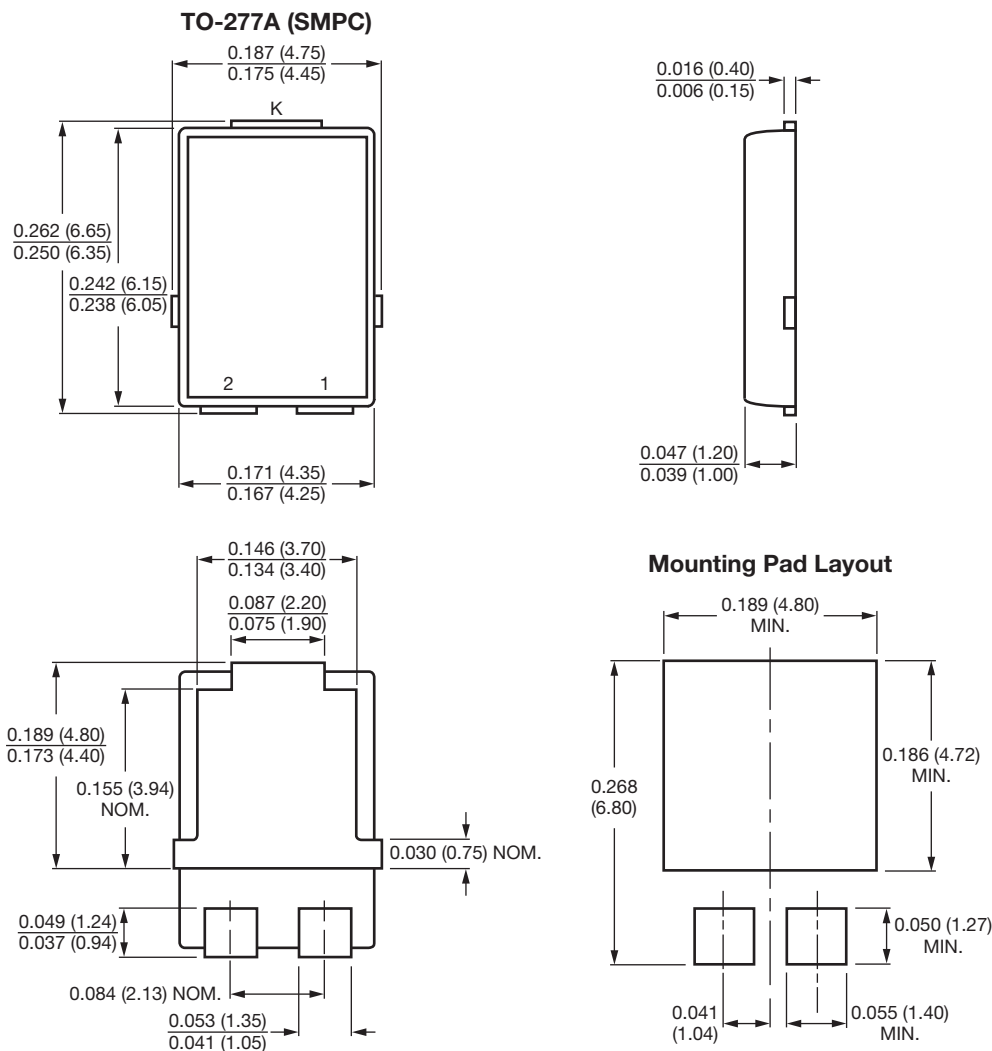
Fig. 4 - Typical Reverse Leakage Characteristics Per Diode

# SS12P4C

Vishay General Semiconductor



## PACKAGE OUTLINE DIMENSIONS in inches (millimeters)



Conform to JEDEC TO-277A



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